

November 2013

FQPF22N30

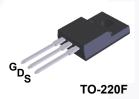
N-Channel QFET[®] MOSFET 300 V, 12 A, 160 m Ω

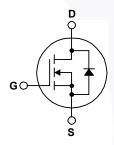
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 12 A, 300 V, $R_{DS(on)}$ = 160 m Ω (Max.) @ V_{GS} = 10 V, I_D = 6 A
- Low Gate Charge (Typ. 47 nC)
- Low Crss (Typ. 40 pF)
- · 100% Avalanche Tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQPF22N30	Unit
V_{DSS}	Drain-Source Voltage		300	V
I_D	Drain Current - Continuous (T _C = 25°C)		12	А
	- Continuous (T _C = 100°C)		7.6	А
I _{DM}	Drain Current - Pulsed	(Note 1)	48	Α
V_{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	1000	mJ
I _{AR}	Avalanche Current	(Note 1)	12	A
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.6	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P _D	Power Dissipation (T _C = 25°C)		56	W
	- Derate above 25°C		0.45	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	FQPF22N30	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.23	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQPF22N30	FQPF22N30	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics

T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Uni
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	300			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.3		V/°C
I _{DSS}	Zara Oata Vallana Busin Ourset	V _{DS} = 300 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 240 V, T _C = 125°C			10	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 6 A		0.12	0.16	Ω
g _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 6 A		12.5		S
C _{oss} C _{rss}	Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$		350 40	450 50	pF pF
orss	Neverse Transier Capacitance			40	30	ρı
Switch	ing Characteristics					ı
t _{d(on)}	Turn-On Delay Time	V _{DD} = 150 V, I _D = 22 A,		35	80	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		230	470	ns
$t_{d(off)}$	Turn-Off Delay Time			85	180	ns
t _f	Turn-Off Fall Time	(Note 4		100	210	ns
Qg	Total Gate Charge	V _{DS} = 240 V, I _D = 22 A,		47	60	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10 V		12		nC
Q_{gd}	Gate-Drain Charge	(Note 4)		24		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				12	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				48	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 12 A			1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 22 A,		215		ns
^		dl / dt = 100 A/v.a		4.0		_

Q_{rr}

Reverse Recovery Charge

μС

1.6

 $dI_F / dt = 100 A/\mu s$

Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature. 2. L = 11.6 mH, I_{AS} = 12 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C. 3. $I_{SD} \le 22$ A, di/dt ≤ 200 A/µs, $V_{DD} \le BV_{DSS}$, starting T_{J} = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

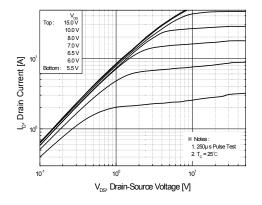
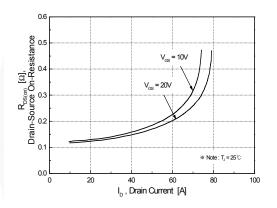


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



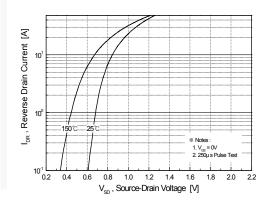
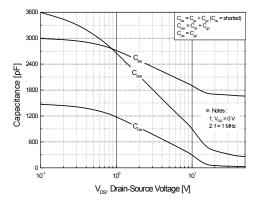


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



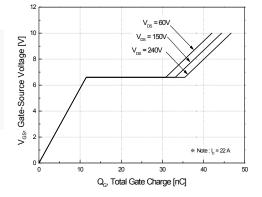
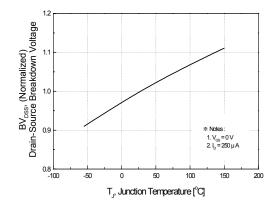


Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics

Typical Characteristics (continued)



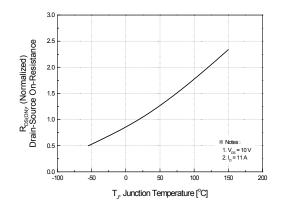
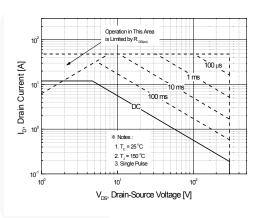


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



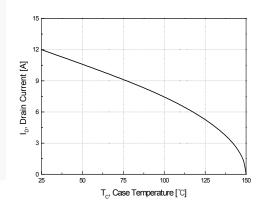


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

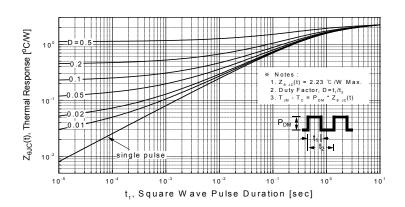


Figure 11. Transient Thermal Response Curve

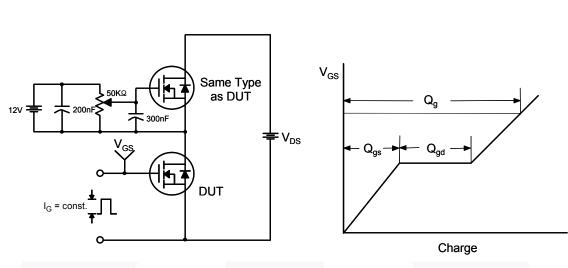


Figure 12. Gate Charge Test Circuit & Waveform

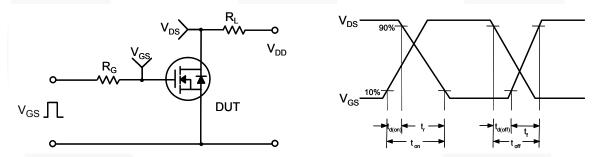


Figure 13. Resistive Switching Test Circuit & Waveforms

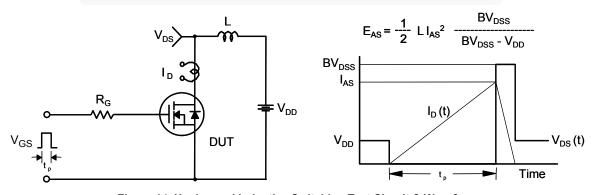
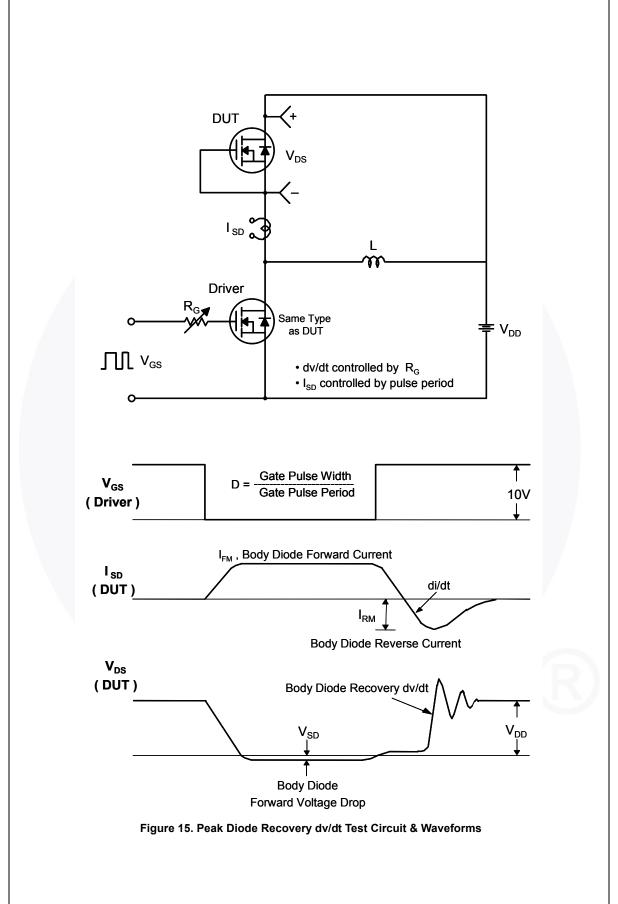


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions

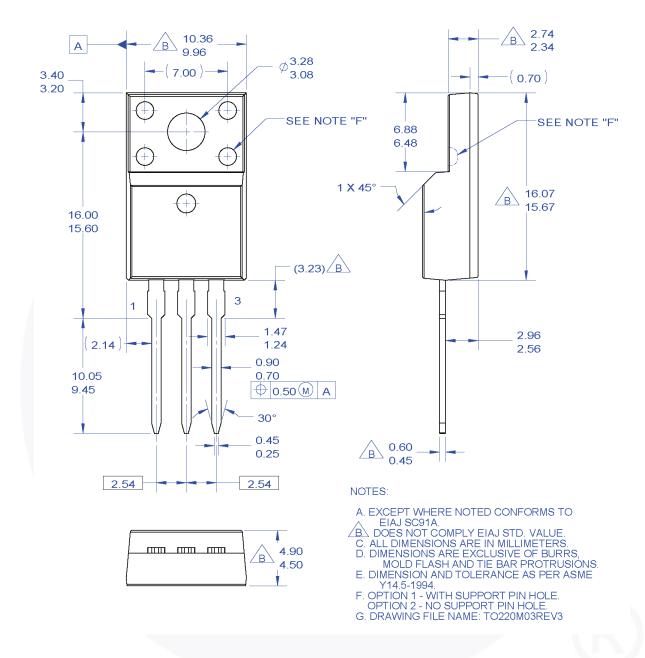


Figure 16. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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